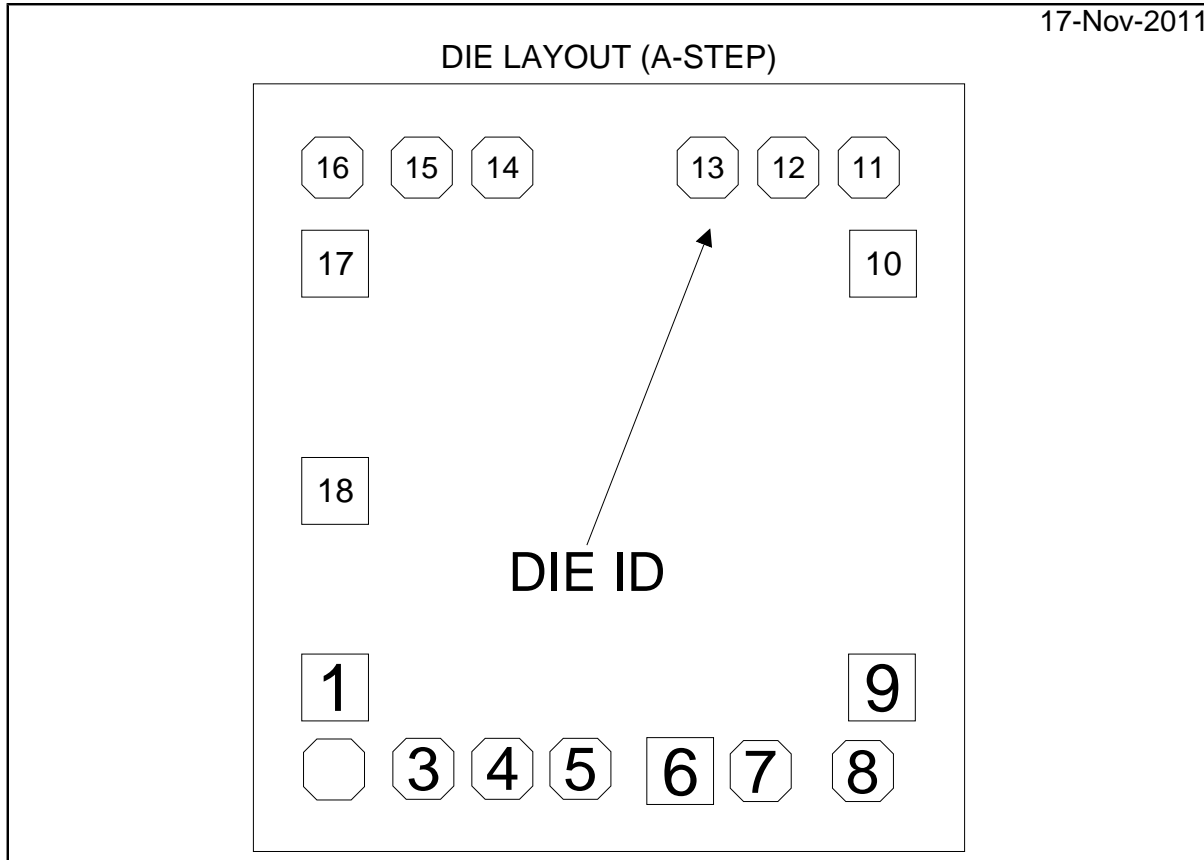


LMP7721-MDC
Femtoampere Input Bias Current Precision Amplifier

17-Nov-2011



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMP7721A	Bond Pad Opening Size (min)	75.05µm x 75.20µm
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDON NITRIDE
Wafer Diameter	203.2mm	Back Side Metal	GOLD
Die Size (Drawn)	800.10µm x 863.60µm 31.5mils x 34.0mils	Back Side Connection	Floating
Thickness	406.4µm Nominal		
Min Pitch	476.80µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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Die Bond Pad Coordinate Locations(A-Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
IN+	1	-308.12	-247.30	75.05	x	75.20
NC	2	-309.35	-339.55	68.60	x	68.60
NC	3	-208.85	-338.80	68.60	x	68.60
NC	4	-120.00	-338.80	68.60	x	68.60
NC	5	-32.15	-338.80	68.60	x	68.60
V-	6	80.08	-341.30	75.05	x	75.20
NC	7	170.70	-341.30	68.60	x	68.60
NC	8	285.70	-341.30	68.60	x	68.60
Vout	9	307.07	-247.30	75.05	x	75.20
V+	10	308.32	229.50	75.05	x	75.20
NC	11	292.25	337.60	68.60	x	68.60
NC	12	201.65	337.60	68.60	x	68.60
NC	13	111.05	337.60	68.60	x	68.60
NC	14	-120.00	337.60	68.60	x	68.60
NC	15	-210.60	337.60	68.60	x	68.60
NC	16	-311.20	337.60	68.60	x	68.60
IN-	17	-308.12	229.50	75.05	x	75.20
NC	18	-308.12	-26.15	75.05	x	75.20

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Notes

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